

## EXTRA COOLING CAPACITIES



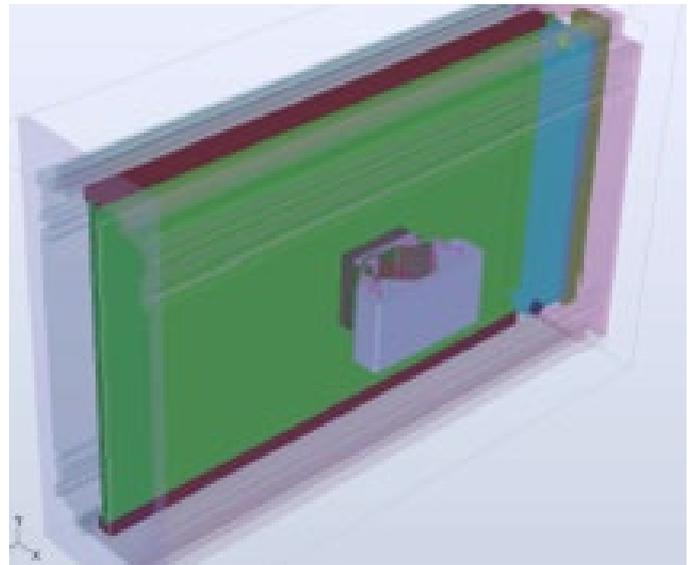
### REQUIREMENT

Test a measurement application which needs additional heat dissipation of a hot spot of one board via FHC to the side panel.



### CHALLENGE

Cool the hot spot of the PCB inside the cassette.



### SOLUTION

Use the side panels with cooling fins. Use the FHC to guide the heat from the hot spot of the PCB through the FHC and the side panel. Reduction of the processor surface temperature by approx. -10 to 12°C.

#### Project Details

Location	Germany
Type of system	Electronic application (Test & Measurement)
Technology	Standard Cassette IEC 60297-3-101...103
Product scope	Series
Date/Time frame	02 / 2016
Contract scope	> 100 boxes per year